

Amendments to the Claims

1-13.(cancelled)

14.(new) A semiconductor die package, comprising a semiconductor die and a permanent protective material surrounding substantially all of the die, the protective material fully curable by exposure to ultraviolet light and shrinking 10% or less by volume upon curing.

15.(new) A semiconductor die package, comprising:
a semiconductor die;
conductive leads electrically connected to the die; and
protective material covering at least a portion of the die and at least a portion of the leads, the protective material fully curable by exposure to ultraviolet light and shrinking 10% or less by volume upon curing.

16.(new) The semiconductor die package of Claim 15, wherein the protective material is formed from a mixture including a polymer resin and a photoactive compound.

17.(new) The semiconductor die package of Claim 16, wherein the polymer resin comprises a phenol-formaldehyde epoxy novolac resin and the photoactive compound comprises triaryl sulfonium hexafluorophosphate.

18.(new) The semiconductor die package of Claim 17, wherein the protective material is formed from a mixture including about 44% by volume phenol-formaldehyde epoxy novolac resin and about 1% by volume triaryl sulfonium hexafluorophosphate.

19.(new) A method, comprising:

coating a semiconductor die with a polymer that is fully curable by exposure to ultraviolet light and shrinks 10% or less by volume upon curing; and exposing the coating to ultraviolet light.

20.(new) The method of Claim 19, wherein coating comprises coating substantially all of the semiconductor die with a polymer that is fully curable by exposure to ultraviolet light and shrinks 10% or less by volume upon curing.

21.(new) A method, comprising:

coating a semiconductor die with a mixture of a phenol-formaldehyde epoxy novolac resin and triaryl sulfonium hexafluorophosphate; and exposing the coating to ultraviolet light.

22.(new) The method of Claim 21, wherein coating comprises coating the semiconductor die with a mixture of about 44% by volume phenol-formaldehyde epoxy novolac resin and about 1% by volume triaryl sulfonium hexafluorophosphate.